| i Number I | | Search Text soler adj ball improve with wire with bond and $25^{\circ}/5^{\circ}$.cols. | DB USPAT; US-PGPUB; EPO; JPO; DERWENT; | Time stamp 2002/10/21 08:25 |
|---------------|--------|--|---|--|
| 1 | : | soler adj ball with improve with wire with bond | US-PGPUE; EPO; JPC; DEEWENT; | 2002/10/21 08:25 |
| 3 | · 1 | solder adj ball with improve with wire with bind | IBM_TDB USPAT; US-PGPUB; EPG; UFG; DERWENT; | 2002/10/21 08:30 |
| 4 | 99 | solder adj ball with wire with bond with connection | IBM_TOB USPAT; US-PGPUE; EPG; JPG; DEFWENT; | 2002/10/21 08:38 |
| c | 24 | solder adj ball with wire with bond with lead | IBM_TDB US:AT; US-PGPUE; EPC; JFC; DEFWENT; | 2002/10/21 08:39 |
| na . | 803 | (257/691).CCLS. | IEM_TDE US:AT; US-PGPCE; EFC; CFC; DEFWENT; | 2002/10/19 16:28 |
| - | 220 | ((257/691).CCLS.) and power with line | IEM_TDE USFAT; US-PGPUB; EPO; JPO; DEFWENT; | 2002/10/17 18:17 |
| - | 208530 | ((257/691).CCLS.) and metallization with over coat | IEM_TDB USTAT; US-PGPUB; EP1; UPO; DEFWENT; | 2002/10/17 18:18 |
| - | 2 | ((257/691).CCLS.) and metallization with overcoat | IBM_TOB USFAT; US-PGPUB; EPD; CPC; DERWENT; IBM_TOB | .2002/10/17 18:19 |
| - | 19 | ((257/691).CCLS.) and metallization with (die IC semiconductor chip' with surface | USIAT; US-PGPUF; EPU; UPO; DERWENT; IBM TOB | 2002/10/17 18:44 |
| - - - | 5 | 5311088.URPN. 5751057.URPN"5227639" "5250840" "5252853" "5252854" "5286999" "5311058" "5358304" "5359224" "5365113" "5394008" "5428247" "5442233" "5461255" "5473190").PN. | USPAT USPAT USPAT | 2002/10/17 18:23 2002/10/17 18:25 2002/10/17 18:26 |
| - | 5 E E | 5461255.URPN. - 287 2071.COLS. | USPAT USPAT; US-FSFUB; EFO; UPO; DERWENT; | 2002/10/17 18:32 2002/10/17 18:47 |
| - | 10 | 257-2077.CCLS. Tand metallization with die TC semidondustor ship with surface | IBM_TOB USPAT; US-PGPUB; EFO; JFO; DEBWENT; IBM_TOB | 2002/10/17 19:47 |

| - | 759 | (257/208).GCLS. | USPAT; US-PGPUE; | 2002/10/17 18:47 |
|--------------|------|--|---|--------------------------------------|
| | | | EPG; JPO; DEFWENT; IBM TDB | |
| - | ć | 257/208).COLS. and metallization with die IO semiconductor chip; with surface | USFĀT; US-PGPUE; | 2002,10/17 18:47 |
| | | | EPG; JPG; DEHWENT; IBM_TDB | |
| - | | 4249192.URPN. 257/660 | | 2002/10/17 18:49 2002/10/18 10:48 |
| | | | US-PGPUB; EBC; UPC; DEFWENT; IBM TOB | |
| - | 3066 | (25%/6+6).CCLS. | US:ĀT; US-PGPUE; EFO; JFC; | 2002,10,18 10:48 |
| | 1050 | ((257/666).CCLS.) AND(metallization lead | FERWENT; IBM_TEB USFAT; | 200::.10 18 10:52 |
| _ | 1039 | line bus : WITH (chip die ic semiconductor integrated adj circuit) WITH surface | • | 200 10, 10 10, 32 |
| | 842 | (((.57/666).CCLS.) AND(metallization lead line bus - WITH (chip die ic semiconductor | IEM_TOP USFAT; | 2002/10/18 10:52 |
| | | integrated adj circuit)WITH surface) AND wire AND lead | EBU; CBU; DERWENT; IBM TIB | |
| - | 796 | ((157.666).CCLS.) AND(metallization lead line bus + WITH (chip die ic semiconductor integrated adj circuit)WITH surface) and wire WITH lead | USFAT; US-PGFUB; EST; CFC; DERWENT; IBM TIB | MCOM, 10 18 10:53 |
| - | 30 | ((257/666).CCLS.) AND(metallization lead line bus + WITH (chip die ic semiconductor integrated adj circuit)WITH surface) and wire WITH lead) AND active WITH element | USFAT; US-PGFUF; EFU; CFC; DEFWENT; | 2002/10 18 11:04 |
| - | 8 | "5:48064" "5150826" "5205463" "5710407" "5717252" "5803246" | IEM_TIE USFAT | 2002/10 18 10:55 |
| - | 13 | "5878338" "5898225").PN. ["4158388" "4862245" "4948754" "511711" "5252853" "5331200" "5384487" "5538920" "5565379" "5589984" "5578526" "5587336" | USPAT | 2002 10/18 10:59 |
| | 2.4 | "5677567").PN. | | 2002 10 18 11:01 |
| - | 155 | 538448".URPN. (((25 7666).CCLS.) AND(metallization lead line bus) WITH (chip die ic semiconductor integrated adj circuit)WITH surface) and | USFAT; US-PGPUB; EFO; JPO; | 2002/10/18 11:35 |
| | | wire WITH lead) AND encapsulate | DEFWENT; IBM_TDB | |
| - | - | ("5167;83" "5428248" "5834837" "5898216" "5977613" "5998877" "6329735").PN. | US: AT | 2002/10/18 11:08 |
| - | | "4546374".PN. | USFAT | |
| - | * * | 4546371.URPN. | USFAT | 2002/10/18 11:12 |
| - | · | 5302849.URFN. | USHAT USHAT | 2002/10/18 11:34 2002/10/18 11:41 |
| | | "577331"\.EX. | | |
| - | į. | 6144100.pm. | USPAT; US PGPUB; EFD; UPO; DERWENT; IBM_TDB | 2002/10/18 13:55 |
| | | | | |

| - | 613162pm. | USPAT; US-PGPUB; EPO; JPG; DERWENT; | 0002/10/0A 13:66 |
|---|---|---|--|
| | 9 - "5492894" . "5578524" - "5668052" "5795921" - "5643816" - "5692968" "5885898" - "8994227" - "6146138" .pm. | IBM_TDB USPĀT | 2002/10/18 13:58 |
| - | 971 word with line with power with ground | USPAT; US-PGPUB; EPG; JPG; DEFWENT; IBM TOB | 2002/10/18 14:63 |
| - | 121 (word with line with power with ground) AME AST (3.00LS. | USPAT; US-PGPUB; EFO; UPO; DERWENT; IBM TDB | 2002/13/18 14:53 |
| - | 9 6066515.URPN. 8 ("5148964" "5150828" "5205463" "5710457" "5717252" : "5803246" "5872338" "5898225").PN. | USPAT USPAT | 2002/10/18 18:29 2002/10/18 18:37 |
| - | 813 (257/691).cols. | USPAT; US-PGPUB; EPC; JPC; DEFWENT; IBM TDB | 2002,10/18 18:39 |
| - | 32 ((257/691).CCLS.) and power with lines with surface | USFAT; US-PGPUE; EFC; JPC; DEFWENT; IEM TDB | 2002,10,718 18:52 |
| | 3 ("5028983", "5256996"; "5550406").PN. 4 5677570.URPN. 33 ("4355456"; "4878098" "4916519" "4948754"; "4949150"; "4993305"; "4993618", "5009721"; "5061985"; "5082801"; "5226582"; "5235212"; "5319224"; "5441917"; "5463255"; "5502337"; "5523626"; "5587607"; "5602420"; "5608245"; "5612570"; "5623154"; "5637920"; "5640048"; "5641978"; "5644166"; "5652467"; "5666008"; "5731634"; "5742100").PN. | USFAT USFAT USFAT | 2002/10/18 18:43 2002/10/18 18:44 2002/10/18 18:47 |
| - | 759 (259/208).ccls. | USPAT; US-PGPUB; EP1; JP0; DEFWENT; IBM TDB | 2002/10/18 18:52 |
| - | 238 - 257-209°.cols. | USEAT; US-PGPUB; EPI; JPO; DEFWENT; IBM TDB | 2002/10/18/19:52 |
| - | <pre>1:</pre> | USEAT; US-PGPUB; EP0; JP0; DERWENT; IBM TOB | 2002/10/18 18:55 |
| - | [::257/209%.CCLS.* and power with lines with surface | USPĀT; US-PGPUB; EPD; JPO; DERWENT; IBM TOB | 2002/10/19 18:55 |
| _ | <pre>0 (0087-2090.00LS. and power with line with surface</pre> | USPĀT; US-PGPUB; EFO; JFO; DERWENT; JBM_TOB | 2002/17/18/18:58 |

| - | 3 166 | 287/468 .CCLS. | USPAT; US-PGPUB; EPC; JPG; DEFWENT; IBM TDB | 2002/10/18/18:55 |
|---|-------|--|--|-------------------|
| - | 13 | '287/666'.0018.' and power with line with surface | USFĀT; US-PGPUB; EFC; UPC; DEFWENT; | 2012/11/18 18:87 |
| - | 253 | .287/666CCLS., and line with surface | IBM_TDB US:AT; US-PGPUE; EPK; JPC; DEFWENT; | 2012/10/16 19:11 |
| - | 605 | power ground with line with surface and 257/\$.cols. | IEM TOB US! AT; US: PGPUB; EFG; JPC; DEHWENT; IBM TOB | 2012/10/16 19:12 |
| - | 88 | ((power ground) with line with surface and 257/\$.ccls.) and lead with frame | USPAT; US-PGPUE; EPC; JPC; DEFWENT; IBM TUB | 2002/10/18 19:26 |
| - | 2 | 5973554.pn. | US: AT; US-PGPUE; EFO; UPC; DERWENT; IBM TOB | 2662/10/21 08:22 |
| - | 2 | 6144100.pn. | USFAT; US-PGPUE; EPO; JPC; DERWENT; IBM TDB | 2002/10/19 16:35 |
| - | 4 | ("5182420" "5367195" "5369220" "5734200").PN. | USEĀT | 2002/10/19 16:40 |
| - | 32€€ | (251/666,.CCLS. | USFAT; USFPGPUF; EPG; CFG; DERWENT; IBM TDE | 2002/10/19 17:53 |
| - | 3 | :(257/666).CCLS.) and art with lead with frame with mounting with pad | US:ĀT; US-PGPUF; EPD; JPC; DERWENT; IBM TDB | 2002/10/19 18:13 |
| - | 5 | conventionally with mounting with pad with lead adj frame and (257/\$).ccls. | | 2002/10/19 18:15 |
| - | ć | conventionally with mounting with pad with lead adj frame | USPAT; US-PGPUB; EP3; JPG; DERWENT; IBM TOB | 2002/10/19 18:16 |
| - | .01 | conventionally with die with pad with lead adf frame | US: AT; US-PGPUB; EF; JFG; DERWENT; IBM_TDB | 00,00/10/19/19:16 |